

# FLAT HEATSINK ASTRIAL KIT

**Annex Manual** 





SYSTEM CERAMICS s.p.a. B.L. SYSTEM ELECTRONICS

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This manual applies to the product codes:

FLAT HEATSINK ASTRIAL KIT 1E000501

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Translation of the original instructions: English

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This product meets the safety requirements of the following standards:

• REACH REGULATION (EU) No.1907/2006. General product safety







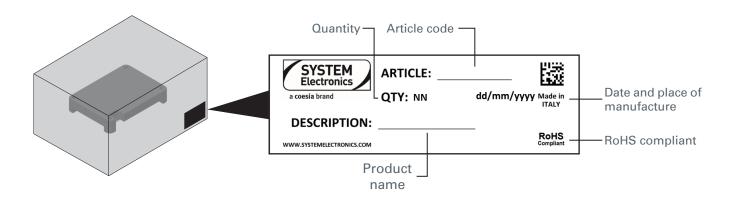
## **General information**

Thank you for choosing FLAT HEATSINK ASTRIAL KIT. KIT consisting of a heatsink, a gap pad, and a fan, which offers two assembly options depending on the support on which it is installed:

- CASE #1 "Carrier without spacers";
- CASE #2 "Carrier with spacers".

Please read this manual and keep it with care. The information it contains will be indispensable for correct installation and safe use. With this manual, SYSTEM ELECTRONICS wishes to establish a cooperative relationship with you in order to perfect our product to make it more versatile for your needs. That is why we kindly ask you to notify us of any errors, oversights, malfunctions, suggestions, comments, opinions, by writing to the contacts you will find in this manual.

## **Product identification**



As stated on the product label, it complies with the following regulations:

RoHS (Restriction of Hazardous Substances): restriction on the use of certain hazardous chemical substances
in Electrical and Electronic Equipment (EEE), such as lead, mercury, cadmium, hexavalent chromium,
polybrominated biphenyls (PBB) and their ethers (PBDE), and certain phthalates.

## **Availability**

For the documentation, see System Electronics.ai





## **Technical support**

EBV, as an authorised reselled of the product, is available for a first level contact to customer and for any additional information or clarification required.

If necessary, please contact (sito EBV)

In case of deeper technical expertise support is needed, the manufacturer support service is available for clarification or contact and intervention by specialists.

## Always specify:

- Customer's name and identification data;
- The product identification data, such as: code and model.

If necessary, please contact:

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## **NOTES**

Always purchase original or equivalent spare parts if authorised in writing by SYSTEM ELECTRONICS





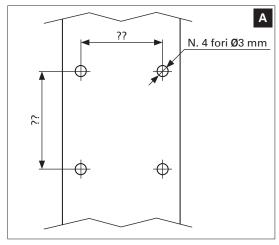
## Assembly sequence: CASE #1 "Carrier without spacers"

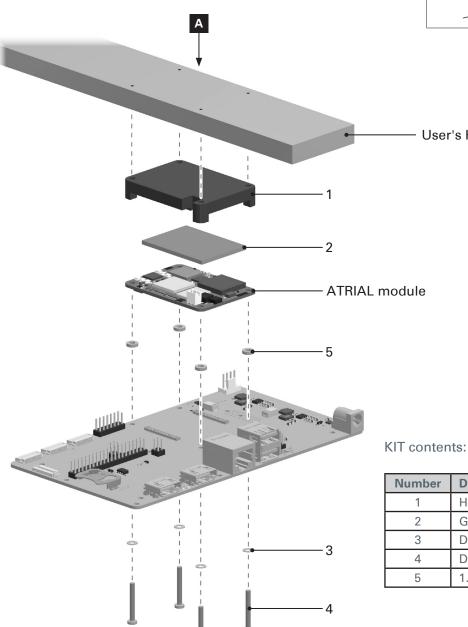
To prevent board damages due to bending please put the provided spacers "50" between Astrial module and carrier board.

Use 4 DIN 7985 M2.5X20 screws "4" and DIN137A M2.6 "3" washers to secure the KIT to the carrier with a tightening torque of 0.4 Nm in order to avoid damage to the module.

## **CAUTION!**

Remove the gap pad protective liners before use. It is not recommended to reuse the gap multiple times.





- User's Heatsink

Number	Description	QTY
1	HEATSPREADER	1
2	GAP PAD ULTRASOFT 2MM	1
3	DIN137A WAVY WASHER M2.6	4
4	DIN 7985 2,5X20 SCREW	4
5	1.5 mm SPACER	4



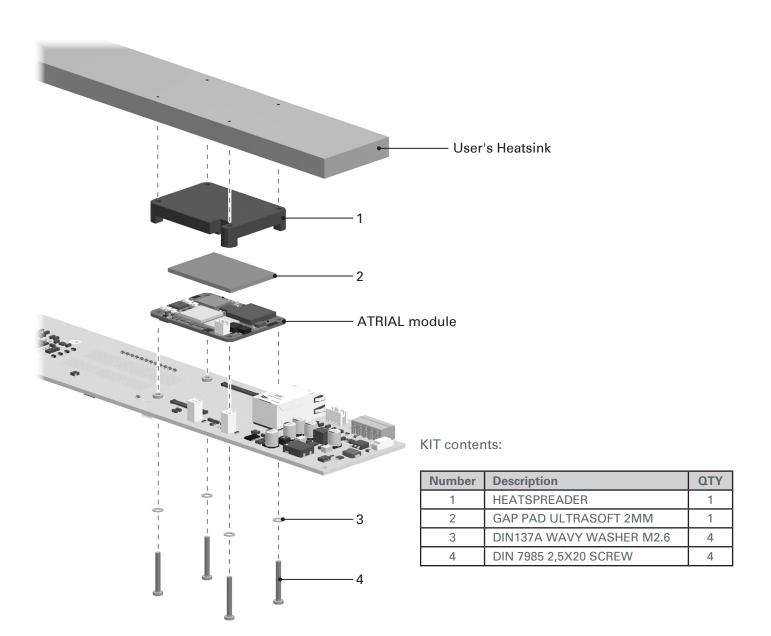


## Assembly sequence: CASE #2 "Carrier with spacers"

Use 4 DIN 7985 M2.5X20 screws "7" and DIN137A M2.6 "6" washers to secure the KIT to the carrier with a tightening torque of 0.4 Nm in order to avoid damage to the module.

## **CAUTION!**

Remove the gap pad protective liners before use. It is not recommended to reuse the gap multiple times.





## **Decommissioning and disposal**

## **DANGER!**

Switch off the power supply before disconnecting the cables and dismantle the parts to be disposed of

The Module must be dismantled and disassembled completely before being disposed of.

- Plastic enclosure parts must be taken to a plastic recycling centre.
- Stainless steel parts must be taken to a metal recycling centre.
- Electronic components and/or printed circuit boards must be disposed of in compliance with national regulations for the disposal of electronic products.

#### **WARNING!**

Dispose of the various materials so that they can be recycled in compliance with the regulations in force in the country of use.

Nationally, the European Union Act 2018 amended Legislative Decree 49/2014, in compliance with Directive 2012/19/EU on waste electrical and electronic equipment (WEEE).







